



(2.54 mm) .100"

HLE SERIES

COST-EFFECTIVE RELIABLE SOCKET

Mates With:
TSW, MTSW, DW,
EW, ZW, TLW, TSM,
MTLW, HW

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLE

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
BeCu
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Current Rating (HLE/TSM):
4.1 A per pin
(2 pins powered)
Voltage Rating:
400 VAC

Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.78 mm) .070" to
(3.43 mm) .135", pass-through,
or (2.59 mm) .102" min
plus board thickness for
bottom entry
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-20)
(0.15 mm) .006" max (21-50)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
Contact Samtec.

Note:
Some lengths, styles and options are non-standard, non-returnable.

HLE	1	NO. PINS PER ROW	02	PLATING OPTION	DV	TAIL OPTION	OTHER OPTION
				<p>-F = Gold flash on contact, Matte Tin on tail</p> <p>-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail</p>	<p>Leave blank for Surface Mount</p> <p>(Requires -BE for Bottom Entry)</p>		<p>-BE = Bottom Entry (N/A with -TE)</p>
				<p>-TE = Through-hole Top Entry</p>		<p>-LC = Locking Clip (2 positions min.) (N/A with -A) (Manual placement required)</p>	
				<p>-PE = Through-hole Pass-through Entry</p>		<p>-K = (6.50 mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with -TE or -PE tail option</p>	
				<p>-TR = Tape & Reel Packaging (29 positions max.)</p>			

02 thru 50

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.